IMT-CE06-SF4
ENCAPSULANT EPOXY

IMT-CE06-SF4 is a single component encapsulant epoxy. This product is formulated as a globtop epoxy to protect IC chip for Chip-On-Board and/or Chip-On-Flex applications. It is designed to fast cure at moderate temperature and offer excellent adhesion strength after cure. IMT-CE06-SF4 also offers excellent heat, moisture and chemical resistance properties.

IMT-CE06-SF4 is non-solvent type and a 100% solid system. It does not contains hazardous, prohibited substances and comply to RoHS3, EU directive 2015/863, Substances of Very High Concern (SVHC) published by ECHA as well as Halogen Free. This product is packed either in syringe or can for automated dispensing.

TYPICAL PROPERTIES*

Cure Conditions	140°C for 60mins 150°C for 30mins
Physical Properties	
Color	Smooth, semi-glossy black after cure
Consistency	Flowable paste
Specific Gravity	1.31
Viscosity @5rpm, 25˚C	49,000cPs
Solid Content	100%
Shore D Hardness	88
Glass Transition Temperature, Tg	≥ 100°C
CTE below Tg (α1)	50ppm
CTE above Tg (α2)	150ppm
Water Absorption @100°C-1h	< 0.5%wt
Operating Temperature	-40°C to 125°C
Electrical & Thermal Properties	
Volume Resistivity	> 1 x 10^{13}Ωcm
Thermal conductivity	0.30W/mK
Ionic Contaminants	
Chloride, Cl-	< 650ppm
Bromine, Br-	Not detected
PVC	Not detected
Pot Life	≥ 2 months at room temperature
Shelf Life	18 months at 0°C or below in closed container

IN-MAT TECHNOLOGIES (S) PTE LTD
623 ALJUNIED ROAD, #05-09, ALJUNIED INDUSTRIAL COMPLEX
SINGAPORE 389835
Tel / Whatsapp / Wechat: +65-8688 8711
E-Mail: sales@inmat-tech.com
Website: www.inmat-tech.com

* The information is based on data and tests believed to be accurate. In-Mat Technologies (S) Pte Ltd makes no warranties as to its accuracy and assumes no liability in connection with the use or inability to use this product.